

Supermicro 3rd Generation Intel Xeon Scalable (Ice Lake Series) PORTFOLIO



Intel 3rd Gen Xeon Scalable

Intel has released their new game-changing generation of CPU processor, the 3rd Gen Xeon Scalable “Ice Lake”, featuring up to 40 cores per socket, an increase of 20% raw performance and improved memory bandwidth through the increase of memory channels from 6 to 8. In addition, the new Intel Optane Pmem 200 Series has provided better performance and metrics to users.



3rd Gen Xeon Scalable “Ice Lake” Family

| Model | Cores | Threads | Base (GHz) | Single Core Turbo (GHz) | All Core Turbo (GHz) | Cache (MB) | TDP (W) | Support for Intel Optane Persistent Memory 200 Series | Intel SGX Enclave capacity per processor | Features |
|--------|-------|---------|------------|-------------------------|----------------------|------------|---------|---|--|---|
| 8380HL | 28 | 56 | 2.9 | 4.3 | 3.8 | 38.5 | 250 | Yes | 512 GB | 4 and 8 Socket Scalable Performance |
| 8380H | 28 | 56 | 2.9 | 4.3 | 3.8 | 38.5 | 250 | Yes | 512 GB | 4 and 8 Socket Scalable Performance |
| 8380 | 40 | 80 | 2.3 | 3.4 | 3 | 60 | 270 | Yes | 512 GB | Optimised for highest-per-core scalable performance and supports maximum Intel SGX Enclave Capacity |
| 8376HL | 28 | 56 | 2.6 | 4.3 | 3.5 | 38.5 | 205 | Yes | | 4 and 8 Socket Scalable Performance |
| 8376H | 28 | 56 | 2.6 | 4.3 | 3.5 | 38.5 | 205 | Yes | | 4 and 8 Socket Scalable Performance |
| 8368Q | 38 | 76 | 2.6 | 3.7 | 3.3 | 57 | 270 | Yes | 512 GB | Liquid Cooled, Supporting Maximum Intel SGX Enclave Capacity |
| 8368 | 38 | 76 | 2.4 | 3.4 | 3.2 | 57 | 270 | Yes | 512 GB | Optimised for highest-per-core scalable performance and supports maximum Intel SGX Enclave Capacity |
| 8362 | 32 | 64 | 2.8 | 3.6 | 3.5 | 48 | 265 | Yes | 64GB | Optimised for highest-per-core scalable performance |
| 8360Y | 36 | 72 | 2.4 | 3.5 | 3.1 | 54 | 250 | Yes | 64GB | Optimised for highest-per-core scalable performance |
| 8360HL | 24 | 48 | 3 | 4.2 | 3.8 | 33 | 225 | Yes | | 4 and 8 Socket Scalable Performance |
| 8360H | 24 | 48 | 3 | 4.2 | 3.8 | 33 | 225 | Yes | | 4 and 8 Socket Scalable Performance |
| 8358P | 38 | 76 | 2.6 | 3.7 | 3.3 | 57 | 270 | Yes | 512 GB | Cloud Optimized for VM Utilisation |
| 8358 | 32 | 64 | 2.6 | 3.4 | 3.3 | 48 | 250 | Yes | 64GB | Optimised for highest-per-core scalable performance |
| 8356H | 8 | 16 | 3.9 | 4.4 | 4.3 | 35.75 | 190 | Yes | | 4 and 8 Socket Scalable Performance |
| 8354H | 18 | 36 | 3.1 | 4.3 | 4 | 24.75 | 205 | Yes | | 4 and 8 Socket Scalable Performance |
| 8353H | 18 | 36 | 2.5 | 3.8 | 3.3 | 24.75 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 8352M | 32 | 64 | 2.3 | 3.5 | 3.1 | 54 | 225 | Yes | 64GB | Media Processing Optimized |
| 8352Y | 32 | 64 | 2.2 | 3.4 | 2.8 | 48 | 205 | Yes | 64GB | Scalable Performance |
| 8352V | 36 | 72 | 2.1 | 3.5 | 2.5 | 54 | 1995 | Yes | 8 GB | Cloud Optimized for VM Utilisation |
| 8352S | 32 | 64 | 2.2 | 3.4 | 2.8 | 48 | 205 | Yes | 512 GB | Supporting Maximum Intel SGX Enclave Capacity |
| 8351N | 36 | 72 | 2.4 | 3.5 | 3.1 | 54 | 225 | Yes | 64GB | Single Socket Optimized, Networking/NFV Optimized |
| 6348H | 24 | 48 | 2.3 | 4.2 | 3.1 | 33 | 165 | Yes | | 4 and 8 Socket Scalable Performance |
| 6348 | 28 | 56 | 2.6 | 3.5 | 3.4 | 42 | 235 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6354 | 18 | 36 | 3 | 3.6 | 3.6 | 39 | 205 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6346 | 16 | 32 | 3.1 | 3.6 | 3.6 | 36 | 205 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6342 | 24 | 48 | 2.8 | 3.5 | 3.3 | 36 | 230 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6338 | 32 | 64 | 2 | 3.2 | 2.6 | 48 | 205 | Yes | 64 GB | Scalable Performance |
| 6338T | 24 | 48 | 2.1 | 3.4 | 2.7 | 36 | 165 | Yes | 64 GB | Long-life use and NEBS-Thermal Friendly |
| 6338N | 32 | 64 | 2.2 | 3.5 | 2.7 | 48 | 185 | Yes | 64 GB | Networking/NFV Optimized |
| 6336Y | 24 | 48 | 2.4 | 3.6 | 3 | 36 | 185 | Yes | 64 GB | Scalable Performance |
| 6334 | 18 | 36 | 3.6 | 3.7 | 3.6 | 18 | 165 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6330 | 28 | 56 | 2 | 3.1 | 2.6 | 42 | 205 | Yes | 64 GB | Scalable Performance |
| 6330N | 28 | 56 | 2.2 | 3.4 | 2.6 | 42 | 165 | Yes | 64 GB | Networking/NFV Optimized |
| 6330H | 24 | 48 | 2 | 3.7 | 2.8 | 33 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 6328HL | 16 | 32 | 2.8 | 4.3 | 3.7 | 22 | 165 | Yes | | 4 and 8 Socket Scalable Performance |
| 6328H | 16 | 32 | 2.8 | 4.3 | 3.7 | 22 | 165 | Yes | | 4 and 8 Socket Scalable Performance |
| 6326 | 16 | 32 | 2.9 | 3.5 | 3.3 | 24 | 185 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6314U | 32 | 64 | 2.3 | 3.4 | 2.9 | 48 | 205 | Yes | 64 GB | Single Socket Optimized |
| 6312U | 24 | 48 | 2.4 | 3.6 | 3.1 | 36 | 185 | Yes | 64 GB | Single Socket Optimized |
| 5320 | 26 | 52 | 2.2 | 3.4 | 2.8 | 39 | 185 | Yes | 64 GB | Scalable Performance |
| 5320H | 20 | 40 | 2.4 | 4.2 | 3.3 | 27.5 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 5320T | 20 | 40 | 2.3 | 3.5 | 2.9 | 30 | 150 | Yes | 64 GB | Long-life use and NEBS-Thermal Friendly |
| 5318Y | 24 | 48 | 2.1 | 3.4 | 2.6 | 36 | 165 | Yes | 64 GB | Scalable Performance |
| 5318H | 18 | 36 | 2.5 | 3.8 | 3.3 | 24.75 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 5318N | 24 | 48 | 2.1 | 3.4 | 2.7 | 36 | 150 | Yes | 64 GB | Networking/NFV Optimized |
| 5318S | 24 | 48 | 2.1 | 3.4 | 2.6 | 36 | 165 | Yes | 512 GB | Supporting Maximum Intel SGX Enclave Capacity |
| 4316 | 20 | 40 | 2.3 | 3.4 | 2.8 | 30 | 150 | | 8 GB | Scalable Performance |
| 4314 | 16 | 32 | 2.4 | 3.4 | 2.9 | 24 | 135 | Yes | 8 GB | Scalable Performance |
| 4310 | 12 | 24 | 2.1 | 3.3 | 2.7 | 18 | 120 | | 8 GB | Scalable Performance |
| 4310T | 10 | 20 | 2.3 | 3.4 | 2.9 | 15 | 105 | | 8 GB | Long-life use and NEBS-Thermal Friendly |
| 4309Y | 8 | 16 | 2.8 | 3.6 | 3.4 | 12 | 105 | | 8 GB | Scalable Performance |

Supermicro X12 Servers

Supermicro has announced the introduction of their comprehensive X12 server portfolio based on the latest 3rd Gen Intel Xeon Scalable series processors. This will feature their wide range of servers, storage systems and workstations with new architecture and modular design to improve systems performance, flexibility and scalability.



What is new with Intel 3rd Gen Xeon Scalable Processors?

The new Intel Ice Lake 3rd Gen series processors is highly optimised for the new generation of Intel Optane persistent memory 200 series. It is the only data-centre CPU with built-in AI acceleration, with many new, built-in performance and security enhancements to speed and better protect your applications and data.

These new features include:

Integration with Intel SGX - helps to protect data and application code in real time from the edge to data centre and multi public clouds. This creates simple collaboration using shared data without the compromise of privacy.

Intel Crypto Acceleration – Increases the performance on encryption-intensive workloads such as SSL web serving, 5G infrastructure, VPN/firewalls, while reducing performance impact of pervasive encryption.

Improved connectivity, storage, software and oneAPI cross-architectural tools – enhancing workload optimised solutions to do more, store more and process more.

intel. Performance Made Flexible
3rd Gen Intel® Xeon® Scalable processors deliver extraordinary performance and security everywhere you need it.

Any Workload... Cloud AI HPC Network IoT

Anywhere... Cloud Data Center Telco Core Telco Edge Telco Access Edge

More Performance and Capacity across the Platform

- 3rd Gen Intel® Xeon® Scalable processor
Up to 40 cores per processor
- Intel® Optane™ persistent memory 200 series
Up to 12 TB system memory per dual CPU server
- Intel® Optane™ SSD P5800X
Breakthrough storage performance

End-to-End Security Innovation

- Help protect sensitive apps and data with Intel® Software Guard Extensions (SGX)
- Speed Data Encryption with Intel® Crypto Acceleration
- Enhance Platform Protection with Intel® Platform Firmware Resilience

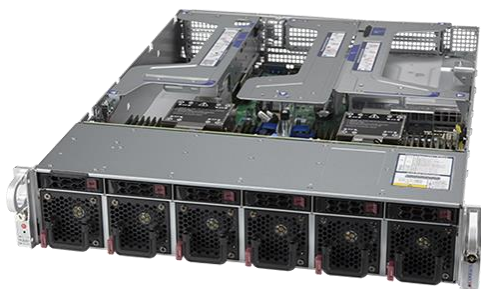
Intel technologies may require enabled hardware, software or service activation. No product or component can be absolutely secure. Your costs and results may vary. © Intel Corporation. Intel, the Intel logo, and other Intel marks are trademarks of Intel Corporation or its subsidiaries. Other names and brands may be claimed as the property of others.

Supermicro 3rd Gen Intel Xeon Scalable Server Portfolio

Supermicro X12 Ultra/Ultra E Servers

The Supermicro 3rd Gen Intel Xeon Scalable-powered Ultra servers provide high performance and flexibility through enterprise applications in a rackmount system.

- Best-in-class server features including all NVMe, hybrid storage and low latency optimisation. Uncompromised performance design with 2 CPU sockets and 32 DIMMs optimised for supporting the highest processor TDPs.



SYS-220U-MTNR

Use Case: Virtualisation, HPC, computing, high end enterprise server, software defined storage, application tier service provider, 5G/telco

2U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 32 DIMM slots, Up to 8TB DRAM, up to 8TB Intel Optane persistent memory 200 series.

Drive: 6x 2.5" NVMe/SAS/SATA drive bays

PCIe: 1 internal PCI-E 4.0 x8 (in x16 slot, LP), 1 PCI-E 4.0 x16 (FH, 10.5"L), 1 PCI-E 4.0 x16 (LP), 5 PCI-E 4.0 x8 (FH, 10.5"L)

Networking: Flexible networking options

Power Supply: 1600W Redundant Titanium level

Additional Features

SYS-220U-TNR

- 22x 2.5" NVMe/SAS/SATA + 2x 2.5" SAS/SATA



SYS-620U-TNR

Use Case: Virtualisation, HPC, computing, high end enterprise server, software defined storage, application tier service provider, 5G/telco

2U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 32 DIMM slots, Up to 8TB DRAM; up to 8TB Intel Optane persistent memory 200 series.

Drive: 12x 3.5" hybrid NVMe/SAS/SATA drive bays

PCIe: 1 PCI-E 4.0 x16 FH, 10.5"L, 5 PCI-E 4.0 x8 FH, 10.5"L, 1 PCI-E 4.0 x8 Internal LP

Networking: Flexible networking options

Power Supply: 1200W Redundant Titanium level



SYS-610U-TNR

Use Case: Virtualisation, HPC, computing, high end enterprise server, software defined storage, application tier service provider, 5G/telco

1U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

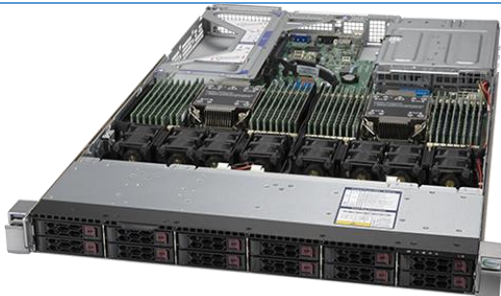
RAM: 32 DIMM slots, Up to 8TB DRAM, up to 8TB Intel Optane persistent memory 200 series; 3200/2933/2666 ECC DDR4 LRDIMM;RDIMM

Drive: 4x3.5" hot-swap hybrid NVMe/SATA/SAS drive bays

PCIe: 1 Internal PCI-E 4.0 x16, 1 PCI-E 4.0 x16 (LP), 2 PCI-E 4.0 x16 (FH, 10.5"L)

Networking: Flexible networking options

Power Supply: 1200W Redundant Titanium level



SYS-120U-TNR

Use Case: Virtualisation, HPC, computing, high end enterprise server, software defined storage, application tier service provider, 5G/telco

1U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 32 DIMM slots, Up to 8TB DRAM, up to 8TB Intel Optane persistent memory 200 series; 3200/2933/2666 ECC DDR4 LRDIMM;RDIMM

Drive: 12x2.5" hot-swap hybrid NVMe/SATA/SAS drive bays

PCIe: 1 Internal PCI-E 4.0 x16, 1 PCI-E 4.0 x16 (LP), 2 PCI-E 4.0 x16 (FH, 10.5"L)

Networking: Flexible networking options

Power Supply: 1200W Redundant Titanium level



SYS-610U-TNR

Use Case: Virtualisation, HPC, computing, high end enterprise server, software defined storage, application tier service provider, 5G/telco

2U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 32 DIMM slots, Up to 8TB DRAM; up to 8TB Intel Optane persistent memory 200 series.

Drive: 4x 3.5" hybrid NVMe/SAS/SATA drives

PCIe: 1 Internal PCI-E 4.0 x16, 1 PCI-E 4.0 x16 (LP), 2 PCI-E 4.0 x16 (FH, 10.5"L)

Networking: Flexible networking options

Power Supply: 1200W Redundant Titanium level

Supermicro X12 GPU & GPU HGX Servers

The Supermicro 3rd Gen Intel Xeon Scalable-powered GPU servers provide high performance and flexibility for AI/ML and HPC applications.

- Features Supermicro's advanced architecture and thermal design, including liquid cooling and custom heatsinks. These 4U GPU systems drive NVIDIA's latest HGX A100 8-GPU baseboard, delivering up to 6x AI training performance and 7x inference workload capacity and highest density.



SYS-120GQ-TNRT

Use Case: Scientific virtualisation, AI/Deep Learning, HPC, Rendering

1U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

Supported GPU: NVIDIA A100,A40, and RTX A6000

RAM: 16 DIMM slots, up to 4TB DRAM; up to 4TB Intel Optane Persistent Memory

PCIe: 6x PCI-e 4.0 x16

Drive: 1x M.2 NVMe or 2x 2.5" NVMe/SATA drives

Networking: 2x 10GbE BaseT port(s)

Power Supply: 2x 2000W Redundant Titanium level



SYS-220GP-TNR

Use Case: Scientific virtualisation, AI/Deep Learning, HPC, VDI

2U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

Supported GPU: NVIDIA A100,A40, and RTX A6000

RAM: 16 DIMM slots, up to 4TB DRAM; up to 4TB Intel Optane Persistent Memory

PCIe: 2x PCI-e Gen 4.0 x8, 6x PCI-e 4.0 x16

Drive: 10x 2.5" hot-swap drives, 2x M.2 NVMe supported, up to 6x 2.5" NVMe/SATA drives

Networking: Flexible networking options

Power Supply: 2x 2600W Redundant Titanium level



SYS-740GP-TNRT

Use Case: Scientific virtualisation, AI/Deep Learning, HPC, Rendering

4U dual socket workstation supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

Supported GPU: NVIDIA A100,A40, and RTX A6000

RAM: 16 DIMM slots, up to 4TB Intel Optane Persistent Memory

PCIe: 1x PCIe 4.0 x8, 6x PCI-e 4.0 x16

Drive: 2x M.2 NVMe/SATA drives, Total 8x 3.5" hot-swap drives, up to 8 NVMe drives (4x NVMe drives default)

Networking: 2x 10GbE BaseT port(s)



Power Supply: 2x 2000W Redundant Titanium level

SYS-420GP-TNR

Use Case: AI/Deep Learning, HPC, Rendering, VDI

4U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

Supported GPU: NVIDIA A100,A40, and RTX A6000

RAM: 32 DIMM slots, up to 8TB DRAM; up to 8TB Intel Optane Persistent Memory

PCIe: 12x PCI-e 4.0 x16

Drive: 16x Hot swap 2.5" SATA/SAS, 2x M.2 NVMe, 8x hot-swap 2.5" NVMe

Networking: 2x 1GbE BaseT with Intel I350

Power Supply: 4x 2000W Redundant Titanium level

GPU HGX Server Features

- Dense and scalable multi-GPU powerhouse that supports the latest HGX A100 8 SXM4 GPUs
- Next generation of NVIDIA NVLink, with double the GPU-to-GPU direct bandwidth, almost 10x higher than PCI-e 4.0
- New NVIDIA NVSwitch that is 2x faster than the previous generation.
- Networking up to 200G, GPUDirect RDMA and GPUDirect Storage



SYS-420GP-TNAR+ (GPU HGX)

NVIDIA CERTIFIED

Use Case: AI/Deep Learning, HPC

4U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

Supported GPU: NVIDIA HGX A100 8

GPU-GPU Interconnect: NVIDIA NVLink with NVSwitch

RAM: 32 DIMM slots, up to 8TB DRAM; up to 8TB Intel Optane Persistent Memory

PCI-E: 10x PCI-e 4.0 x16

Drive: 2x M.2 NVMe/SATA drives, 6x 2.5" hybrid NVMe/SATA/SAS drives

Networking: 2x 10GbE BaseT with Intel X550-AT2 (optional)

Power Supply: 2x 2200W Redundant Titanium level

Supermicro X12 Mainstream Servers

The Supermicro 3rd Gen Intel Xeon Scalable-powered Mainstream servers are versatile entry level and volume systems optimised for enterprise applications.

- Allows enterprise IT managers to choose the exact model for their applications, with a precise set of integrated features needed for their applications.
- These powerful yet cost-effective systems provide excellent flexibility and value at entry-level price points.



SYS-620P-TR

Use Case: Virtualisation, enterprise, data-centre optimised, application and data serving, model analysis, compute intensive applications.

2U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 18 DIMM; Up to 4TB PMem and DRAM, Intel Optane Persistent memory 200 series, 3200MHz ECC

LRDIMM/RDIMM DDR4

PCIE: 6 PCI-e expansion slots

Drive: 8x 3.5" SATA drives

Networking: Dual 1GbE LAN ports

Power Supply: 1200W Redundant Power Supplies
Titanium Level

SYS-620P-TRT

- Dual 10GbE LAN ports



Additional Features



SYS-740P-TR

Use Case: Enterprise, application and data serving, model analysis, compute intensive applications, office environment.

4U form factor dual socket workstation supporting:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 18 DIMM slots, up to 4TB PMem and DRAM, Intel Optane Persistent memory 200 series, 3200MHz ECC

LRDIMM/RDIMM DDR4

PCIE: 6 PCI-E expansion slots

Drive: 8x 3.5" SATA drives

Networking: Dual 1GbE LAN ports

Power Supply: 1000W/1200W 1U Redundant Power Supply
Titanium Level

SYS-740P-TRT

- Dual 10GbE LAN ports



Additional Features



SYS-220P-C9R

Use Case: HPC, enterprise, data-centre optimised, database processing and high density storage, application-optimised solution.

2U dual socket workstation supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 18 DIMM slots, up to 4TB PMem and DRAM, Intel Optane Persistent memory 200 series

PCI-E: 5 PCI-e expansion slots

Drive: 16x 2.5" SATA drives, 1 M.2 NVMe

Networking: Dual 1GbE LAN ports

Power Supply: 1200W Redundant Power Supplies
Titanium Level

SYS-220P-C9RT

- Dual 10GbE LAN ports

Additional Features



Supermicro X12 SuperStorage Solutions

The Supermicro 3rd Gen Intel Xeon Scalable-powered storage solutions provide high performance and are application optimised.

- Powerful yet cost-effective systems that provide excellent flexibility and value at entry-level price points. Optimised for data availability with Supermicro's new drawer design and hot swappable drivers, power supplies and fans. Designed for ease of deployment maintenance with data centre operations in mind.



Additional Features

SSG-620P-ACR12H

Use Case: Enterprise, ISCSI SAN, HPC, database processing & storage, corporate database

2U form factor dual socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16 DIMM ECC DDR4-3200 + 2 Intel Optane

Persistent Memory dedicated slots UP to 18TB: PMem

UP to 4TB: 16x 256 GB DRAM

Drive: 12x 3.5" SATA/SAS drives (4x NVMe hybrid ports), onboard 1x M.2 NVMe

RAID Controller: Broadcom 3916 controller

PCIe: 2 PCI-E 4.0 x8 LP, 4 PCI-E 4.0 x16 LP

Power Supply: 1200W Redundant Power Supplies

SSG-620P-ACR12L

- Broadcom 3816 controller



SSG-620P-ACR16H

- **Drive:** 16x 3.5" hot-swap NVMe/SATA/SAS drive bays (4x 3.5" NVMe hybrid)
- 1600W Redundant Power Supplies Titanium Level



SSG-620P-ACR16L

- Broadcom 3816 controller
- 1600W Redundant Power Supplies Titanium Level



SSG-640P-E1CR24H

Use Case: Enterprise, ISCSI SAN, HPC, database processing & storage, corporate database, appliance optimised storage building blocks.

4U form factor dual socket workstation supporting:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16x ECC DDR4-3200 + 2 Intel Optane Persistent

Memory dedicated, UP to 18TB: PMem

UP to 4TB: 16x 256 GB DRAM

Memory Type: ECC DDR4 RDIMM;LRDIMM;DCPMM

Drive: 24x 3.5"/2.5" SATA/SAS drives, 1x M.2 NVMe

RAID Controller: Broadcom 3908 controller

PCIe: 2 PCI-E 4.0 x8 LP, 4 PCI-E 4.0 x16 LP



Networking: 2x 10GbE BaseT with Intel X550

Additional Features

SSG-640P-E1CR24L

- Broadcom 3808 controller



Supermicro X12 BigTwin Systems

The Supermicro 3rd Gen Intel Xeon Scalable-powered BigTwin system provide a highly modular and tool-less design.

- Superior performance and serviceability with modular mid-plane through PCI-e Next Gen Storage controller options. The multi-node BigTwin with shared components can be more cost effective than standard 1U servers.



SYS-620BT-HNTR

Use Case: Hyperconverged Infrastructure, Container Storage, Scale-Out File Server

Four hot-pluggable nodes in a **2U** Dual socket form factor. Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 20 DIMM slots (16 DRAM + 4PMem), up to 6TB 8x 256GB DRAM and 8x 512GB Intel Optane persistent memory 200 series. 3200MHz ECC DDR4 RDIMM

Drive: 3x 3.5" NVMe/SAS/SATA drive bays, 2 M.2 NVMe OR 2 M.2 SATA3

RAID Controller: Intel SATA,

PCIe: 2 PCI-E 4.0 x16 LP

Networking: Flexible networking options

Power Supply: 2600W Redundant Titanium level power supplies

SSG-620BT- HNC8R

- Broadcom 3808

Additional Features



SYS-220BT-HNTR

Use Case: Diskless HPC clusters, Container-as-a-service; application accelerator, All-Flash NVMe hyperconverged infrastructure, High-Performance File System

Four hot-pluggable nodes in a **2U** Dual socket form factor. Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 20 DIMM slots (16 DRAM + 4PMem), up to 6TB 8x 256GB DRAM and 8x 512GB Intel Optane persistent memory 200 series. 3200MHz ECC DDR4 RDIMM

Drive: 6x 2.5" NVMe/SATA drive bays, 2 M.2 NVMe OR 2 M.2 SATA3

Controller: Intel SATA,

Networking: Flexible networking options

PCIe: 2 PCI-E 4.0 x16 LP

Power Supply: 2600W Redundant Titanium level power supplies



Additional Features

-

SYS-220BT-HNC9R

- Use cases: Mission Critical HPC, Virtualized Big Data Analytics, High-Density Storage RAID Array
- 1 PCI-E 3.0 x8 M.2 NVMe Boot Controller via AOC-SMG3-2M2-B
- Broadcom 3908



SYS-220BT-HNC8R

- Use cases: Container-as-a-Service; Application Accelerator, Diskless HPC Clusters, All-Flash Hyperconverged Infrastructure
- **Storage controller:** Broadcom 3808



SYS-220BT-DNC8R

Use Case: All-Flash Hyperconverged Infrastructure, All-Flash Storage Area Network, All-Flash Object Storage

Two hot-pluggable nodes in a **2U** Dual socket form factor. Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 20 DIMM slots (16 DRAM + 4PMem), up to 6TB 8x 256GB DRAM and 8x 512GB Intel Optane persistent memory 200 series. 3200MHz ECC DDR4 RDIMM

Drive: 12x 2.5" hot-swap NVMe/SATA/SAS drive bays (12x 2.5" NVMe hybrid), 2 M.2 NVMe OR 2 M.2 SATA3

RAID Controller: Intel SATA, Broadcom 3816 (IT mode)

Networking: Flexible networking options

PCIe: 1 PCI-E 3.0 x8 M.2 NVMe Boot Controller via AOC-SMG3-2M2-B, 1 PCI-E 4.0 x16 (LP) slot; 1 PCI-E 4.0 x8 (LP) slot

Power Supply: 2200W Redundant Titanium level power supplies, Shared Power Design

Supermicro X12 FatTwin Systems

The Supermicro 3rd Gen Intel Xeon Scalable-powered FatTwin systems provide advanced multi-node 4U Twin architecture with 8 and 4 nodes, optimised for high density compute.

- The X12 FatTwin architecture provides flexibility and system accessibility for unique data centre requirements.
- Features unique one-half width nodes that provides 2 nodes per rack unit, allowing for modularised left and right nodes with redundant power supplies for maximum reliability.
- Each node supports dual 3rd Gen Intel Xeon Scalable processors.

SYS-F610P2-RTN

Use cases: Telco Data Centre and ETSI certified, virtualisation, scale-out storage, data centre enterprise application, HPC and big data, hyperscale/hyperconverged.



Eight hot-pluggable nodes in a **4U** dual socket form factor.

Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16 DIMM slots, UP to 2TB: 8x 128 GB DRAM, up to 4TB Intel Optane Persistent Memory

PCIE: 6x PCI-e 4.0 x16

Drive: 6 or 8 2.5" NVMe/SATA/SAS drives, 2 M.2 internal drives

Networking: Flexible networking options

Power Supply: 2200W Redundant Power Supplies
Titanium Level

SYS-F620P3-RTBN

Use Case: High capacity and ultra-dense storage, Telco Data Centre and ETSI certified, virtualisation (vSAN), data centre enterprise application, HPC and big data, hyperscale/hyperconverged.



Four hot-pluggable nodes in a **4U** dual socket form factor.

Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16 DIMM slots, to 4TB DDR 4-3200, up to 4TB Intel Optane Persistent Memory,

Drive: 8x 3.5" SATA/SAS drives; 6x 2.5" NVMe hybrid drives, or 8x 2.5" 7mm drive bays

Networking: Flexible networking options

Power Supply: 2x 2200W Redundant Power Supplies
Titanium Level

Supermicro X12 TwinPro Systems

The Supermicro 3rd Gen Intel Xeon Scalable-powered TwinPro system provides a cost-effective 2U multi-node platform.

- The X12 TwinPro systems are designed for simplified deployment and maintenance, and are assembled with the highest quality to ensure continuous operation even at maximum capacity.
- Optimised thermal design for maximum power efficiency.



SYS-220TP-HTTR

Use Case: High Performance Computing, Hyper-Converged Infrastructure, Big Data / Big Science, Oil immersion, Liquid Cooling.

Four hot-pluggable nodes in a **2U** Dual socket form factor.

Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16x DIMMs, Up to 4TB 3DS ECC DDR4-3200 LRDIMM/RDIMM

Drive: 6x 2.5" SATA hybrid drives

Storage Controller: Intel SATA

PCIe: 2 PCI-E 4.0 x16 (LP), 1 PCI-E 4.0 x8 (with M.2 adapter installed)

Networking: Intel X710 Dual port 10GBase-T LAN onboard

Power Supply: 2x 2200W Redundant Power Supplies Titanium Level

Additional Features

SYS-220TP-HC0TR

- 6x 2.5" SATA/SAS hybrid drives
- Broadcom 3008

SYS-220TP-HC1TR

- 6x 2.5" SATA/SAS hybrid drives
- Broadcom 3108





SYS-620TP-HTTR

Use Case: High Performance Computing, Hyper-Converged Infrastructure, Big Data / Big Science, Oil immersion, Liquid Cooling.

Four hot-pluggable nodes in a **2U** Dual socket form factor.

Each node supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16x DIMMs, Up to 4TB DDR4-3200MHz

Drive: 3x 3.5" SATA/SAS hybrid drives

Networking: Intel X710 Dual port 10GBase-T LAN onboard

Storage Controller: Intel SATA

PCIe: 2 PCI-E 4.0 x16 (LP), 1 PCI-E 4.0 x8 (with M.2 adapter installed)

Power Supply: 2x 2200W Redundant Power Supplies
Titanium Level

Additional Features

SYS-620TP-HC0TR

- Broadcom 3008

SYS-620TP-HC0TR

- Broadcom 3108



Supermicro X12 SuperWorkstations

The Supermicro 3rd Gen Intel Xeon Scalable-powered SuperWorkstations provides workstations that are optimised for high performance workloads and applications that require powerful compute and graphics capabilities.

- The X12 SuperWorkstations support multiple NVIDIA GPUs to boost productivity and creativity for professional artists, designers, and engineers across industries such as manufacturing, media and entertainment and energy.



SYS-740A-T

Use Case: Rendering, CAD, Multimedia/Digital Content creation, Engineering/scientific research.

4U Dual socket Workstation supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

GPU: 2x double-width GPUs

RAM: 16x DIMMs, Up to 4TB DDR4-3200MHz RDIMM, LDIMM,LRDIMM

Drive: 8x 3.5" hybrid SATA drives (SAS/NVMe optional), 2 M.2 NVMe

PCIe: 5 PCI-E 4.0 x16, 1 PCI-E 4.0 x8, 2 NVMe M.2 slots

Networking: 2x 1GbE port(s)

Power Supply: 1200W Redundant Power Supplies Titanium Level



SYS-730A-I

Use Case: Rendering, CAD, Multimedia/Digital Content creation, Engineering/scientific research

Mid-Tower Dual socket Workstation supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

GPU: 2x double-width GPUs

RAM: 16x DIMMs, Up to 4TB DDR4-3200MHz, RDIMM, LDIMM,LRDIMM

Drive: 4x internal 3.5" SATA rotating drive bays for easy access, Optional 4 U.2 NVMe drive support, 2 M.2 NVMe

PCIe: 5 PCI-E 4.0 x16, 1 PCI-E 4.0 x8, 2 NVMe M.2 slots

Networking: 2x 1GbE port(s)

Power Supply: 1200W Redundant Power Supplies Platinum Level

Supermicro X12 MP



SYS-240P-TNRT (2U Quad Socket)

Use Case: Artificial Intelligence (AI), Business Intelligence, ERP, CRM, Scientific Virtualization, In-Memory Database, HCI, SAP HANA

2U QUAD socket system supports the following:

CPU: QUAD 3rd Gen Intel Xeon Scalable processors

RAM: 48x DIMMs, Up to 12TB DDR4-3200MHz, LRDIMM/RDIMM/Intel DCPMM

Drive: Up to 24 Hot-swap 2.5" NVMe/SAS3/SATA3 drive bays (Default with 8 SAS3/SATA3 drive bays); Onboard 2x M.2 SATA.

Networking: 2x 10GbE BaseT + 2x 10GbE SFP+ with Intel X710-TM4 (Optional) AIOM 100G QSFP 28

PCIe: 4 PCI-E 3.0 x16 FHHL, 2 PCI-E 3.0 x8 FHFL, 4 PCI-E 3.0 x8 LP (Optional)

Power Supply: 2000W Redundant Power Supplies Titanium Level

Supermicro X12 WIO Servers

The Supermicro 3rd Gen Intel Xeon Scalable-powered WIO servers are the industry's widest variety of I/O optimised servers.

- Delivers optimised systems for specific requirements in storage and networking alternatives that help in accelerating performance, increasing efficiency for application.
- Customisable configurations and optimisations for multiple application requirements, providing attractive cost advantages and investment protections.

SYS-510P-M

Use Case: Small business, web/hosting application, email/firewall/print server.

1U form factor single socket system supports the following:

CPU: Single 3rd Gen Intel Xeon Scalable processors, up to 220 TDP

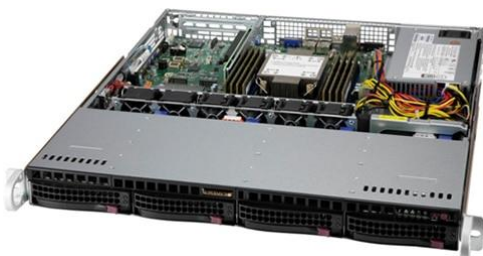
RAM: 8x DIMMs, UP to 2TB: 8x 256 GB DRAM, UP to 3TB: 4x 256 GB DRAM and 4x 512 GB PMem, Memory Type: 3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM, Intel Optane persistent memory 200 series

Drive: 4x 3.5" hybrid SATA/NVMe drives, 2x M.2 PCI-E 3.0 x 4 and SATA

PCIe: 1x PCIe 4.0 x16

Networking: 2x 1GbE BaseT with Intel i350

Power Supply: 500W Redundant Power Supply Platinum Level



Additional Features

SYS-510P-MR

- 400W Redundant Power Supply Platinum Level



SYS-510P-WT

Use case: Virtualisation, cloud computing, enterprise server, data centre optimised

- 2x PCIe 4.0 x16 (FHFL slot), 1x PCIe 4.0 x16 (LP) slot
- 600W Redundant Power Supply Platinum Level



SYS-510P-WTR

Use case: Virtualisation, cloud computing, enterprise server, data centre optimised

- 2x PCIe 4.0 x16 (FHFL slot), 1x PCIe 4.0 x16 (LP) slot.
- 500W Redundant Power Supply Platinum Level.



SYS-110P-WTR

Use Case: Virtualisation, cloud computing, enterprise server, data centre optimised, database processing and storage

1U form factor single socket system supports the following:

CPU: Single 3rd Gen Intel Xeon Scalable processors

RAM: 8x DIMMs, UP to 2TB: 8x 256 GB DRAM, UP to 3TB: 4x 256 GB DRAM and 4x 512 GB PMem, Memory Type: 3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM, Intel Optane persistent memory 200 series

Drive: 10x 3.5" SATA drives with 4 hybrid NVMe/SATA drives, 1x M.2 PCI-E 3.0 x 4 and SATA

PCI-E: 2x PCIe 4.0 x16 (FHFL) slots, 1 PCI-e 4.0 x16 (LP) slot

Networking: 2x 10GbE BaseT with Intel X550

Power Supply: 750W Redundant Power Supply Platinum Level



SYS-520P-WTR

Use Case: Data centre optimised, database processing and storage, network appliance

2U form factor single socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 8x DIMMs, UP to 2TB: 8x 256 GB DRAM, UP to 3TB:

4x 256 GB DRAM and 4x 512 GB PMem, Memory Type:

3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM, Intel

Optane persistent memory 200 series

PCIE: 2x PCIe 4.0 x16 (FHFL) slots, 2 PCI-e 4.0 x16 (LP) slot

Drive: 8x 3.5" SATA drive bays (2x 2.5" NVMe dedicated), 1x

M.2 PCI-E 3.0 x 4 and SATA

Networking: 2x 10GbE BaseT with Intel X550

Power Supply: 600W/650W Redundant Power Supply

Platinum Level



SSG-520P-ACTR12H

Use Case: Enterprise server, database processing and storage, appliance optimised storage.

2U form factor single socket system supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 8x DIMMs, UP to 2TB: 8x 256 GB DRAM, UP to 3TB:

4x 256 GB DRAM and 4x 512 GB PMem, Memory Type:

3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM, Intel

Optane persistent memory 200 series

Drive: 12x 3.5" SAS/SATA drives, 1x NVMe/SATA M.2; 2x

Hot-swap 2.5" NVMe Gen 4/SATA (rear, optional)

RAID Controller: Broadcom 3916/3816

PCIE: 2x PCIe 4.0 x16 (FHFL) slots, 2 PCI-e 4.0 x16 (LP) slot

Networking: Intel Ethernet Controller X550 2x 10GbE

RJ45

Power Supply: 800W Redundant Power Supply Platinum

Level



SSG-540P-E1CTR36L

Use Case: Enterprise server, database processing and storage, appliance optimised storage

4U single socket workstation supports the following:

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 8x DIMMs, UP to 2TB: 8x 256 GB DRAM, UP to 3TB: 4x 256 GB DRAM and 4x 512 GB PMem, Memory Type: 3200/2933/2666MHz ECC DDR4 RDIMM;LRDIMM, Intel® Optane™ persistent memory 200 series

Drive: 36x 3.5" SAS/SATA drives, onboard 1x NVMe/SATA M.2, 2x 2.5" SATA or NVMe drive bays (optional)

Raid Controller: Broadcom 3808

PCI-E: 2x PCIe 4.0 x16 (FHFL) slots, 2 PCI-e 4.0 x16 (LP) slot

Networking: Intel Ethernet Controller X550 2x 10GbE RJ45

Power Supply: 1200W Redundant Power Supplies Titanium Level

Additional Features:

SSG-540P-E1CTR36H

- Broadcom 3908



Supermicro X12 SuperBlades

The Supermicro 3rd Gen Intel Xeon Scalable-powered SuperBlades are the highest density x86 multi-node server with resource saving architecture for enterprise cloud and HPC applications.

- Shared cooling, power and networking infrastructure is the key to high density and server efficiency within these blade solutions. With high performance, density optimised and energy efficiency.
- SuperBlades can significantly reduce initial capital and operational expenses for many organisations. Optimising TCO of key components such as free-air cooling, power efficiency, node density and networking management.



Additional Features

SBI-420P-1C2N

Use Case: Data centre, HPC applications

200 CPUs per 42U Rack

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 16 DIMM slots, up to 4TB DDR4-3200

RDIMM/LRDIMM

Drive: 2x 2.5" hybrid NVMe/SAS/SATA drives; 1 NVMe M.2

Networking: Dual 25G onboard Ethernet

SBI-420P-1T3N

- 2x 2.5" hybrid NVMe/SAS/SATA drives; 1x 2.5" SATA drive, 1 NVMe M.2

SBI-420P-4T2N

- 280 CPUs per 42U Rack



SBI-610P-1C2N

Use Case: Cloud services, simulation & modelling, AI inferencing, HPC

70 CPUs per 42U Rack

CPU: Single 3rd Gen Intel Xeon Scalable processors

RAM: 16 DIMM slots, up to 4TB DDR4-3200

Drive: 2x 2.5" hybrid NVMe/SAS/SATA drives; 1 NVMe/SATA M.2

Networking: Dual 25G onboard Ethernet



Additional Features

SYS-610P-1T2N

- 2x 2.5" hybrid NVMe/SAS/SATA drives; 1x NVMe/SATA M.2, 2x NVMe M.2





SBI-620P-1C3N

Use Case: Cloud Service, Simulation & Modeling, AI Inferencing, High-performance Computing (HPC)

140 CPUs per 42U Rack

CPU: Dual 3rd Gen Intel Xeon Scalable processors

RAM: 32 DIMMs; up to 8TB 3DS ECC DDR4-3200MHz RDIMM/LRDIMM

Drive: 2x 2.5" NVMe + 1x SAS/SATA drives or 3x SATA/SATA

RAID Controller: Broadcom 3108

Networking: Dual 25G onboard Ethernet

Our Partnership with Supermicro



SUPERMICRO is a global IT leader in high performance, high efficiency and green server technology and innovations, growing from a Silicon Valley start-up to a multi-billion-dollar Fortune 1000 company. They have pioneered towards the development of end-to-end green computing solutions to Data Centres, Enterprise IT, Big Data, High-Performance Computing, embedded markets and various industries.

SUPERMICRO provides the broadest range of high-quality products to choose from, this includes Motherboards, Power Supplies, Chassis and Accessories. They are dedicated in providing high quality, reliability and environmentally-friendly solutions.

DiGiCOR partners with Supermicro to give you that platform where your business has access to all of Supermicro Australia's cutting-edge technology for solutions that meet the demands of your data-driven business objectives.

TALK TO US TODAY

DiGiCOR

<https://digicor.com.au>
<https://digicor.co.nz>

DIGICOR SYDNEY

15/8 Avenue of America, Newington,
New South Wales 2127
+61 (02) 9648 6800
sydney@digicor.com.au

DIGICOR BRISBANE

7/160 Lytton Rd, Morningside
Queensland 4170
+61 (07) 3217 9800
brisbane@digicor.com.au

DIGICOR PERTH

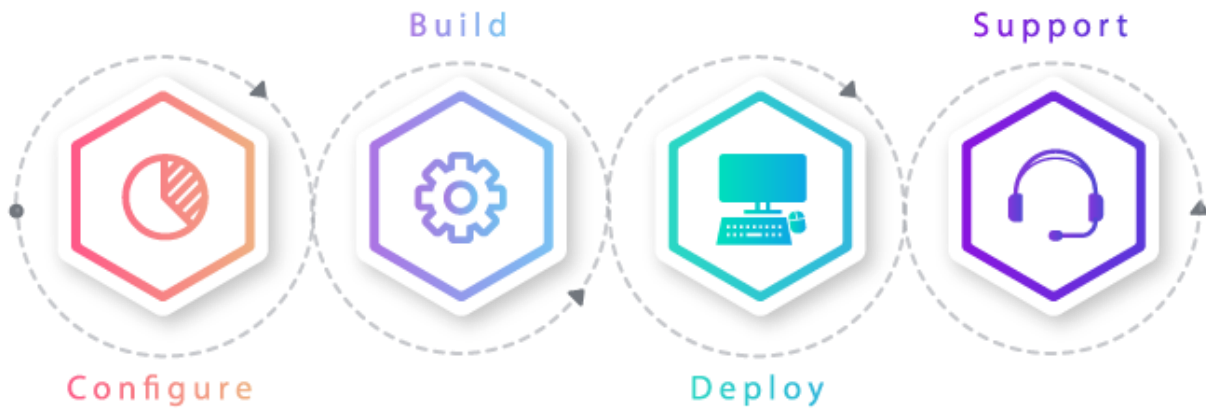
8/8 Welshpool Road, East Victoria Park
Western Australia 6101
+61 (08) 9361 2626
perth@digicor.com.au

DIGICOR MELBOURNE (HQ)

10 Stamford Road, Oakleigh,
Victoria 3166
+61 (03) 9567 8300
melbourne@digicor.com.au

DIGICOR NEW ZEALAND

7/39 Apollo Drive, Rosedale,
Auckland 0632
+64 6477 0823
sales@digicor.co.nz



Configure

- Our system **configurator** helps customers design a tailored computing solution that best fits their needs.
- The smart configurator provides helpful prompts to ensure that any design is validated.

Build

- Our strict **quality assurance process** during assembly and testing ensures that systems leaving our build centre are free-from-defect and are operating as designed.

Deploy

- Our **Australia & New Zealand** wide deployment services and support network means that where-ever you are, you experience smooth deployment.

Support

- Our support team is available to assist in resolving and troubleshooting any issues, with additional warranty support options such as **Next Business Day** or **24/7** service available should you need it.

FOLLOW US



<https://www.linkedin.com/company/digicor-pty-ltd/>



https://twitter.com/DiGiCOR_AUS



<https://www.facebook.com/Digicor-1934945686717615/>



https://www.youtube.com/channel/UC1xIKvhmts_LOWD7Dap16-Q

Australia Sales : 1-300-192-308

New Zealand Sales : (+64) 9477 0823

| Model | Cores | Threads | Base (GHz) | Single Core Turbo (GHz) | All Core Turbo (GHz) | Cache (MB) | TDP (W) | Support for Intel Optane Persistent Memory 200 Series | Intel SGX Enclave capacity per processor | Features |
|---------------|-------|---------|------------|-------------------------|----------------------|------------|---------|---|--|---|
| 8380HL | 28 | 56 | 2.9 | 4.3 | 3.8 | 38.5 | 250 | Yes | 512 GB | 4 and 8 Socket Scalable Performance |
| 8380H | 28 | 56 | 2.9 | 4.3 | 3.8 | 38.5 | 250 | Yes | 512 GB | 4 and 8 Socket Scalable Performance |
| 8380 | 40 | 80 | 2.3 | 3.4 | 3 | 60 | 270 | Yes | 512 GB | Optimised for highest-per-core scalable performance and supports maximum Intel SGX Enclave Capacity |
| 8376HL | 28 | 56 | 2.6 | 4.3 | 3.5 | 38.5 | 205 | Yes | | 4 and 8 Socket Scalable Performance |
| 8376H | 28 | 56 | 2.6 | 4.3 | 3.5 | 38.5 | 205 | Yes | | 4 and 8 Socket Scalable Performance |
| 8368Q | 38 | 76 | 2.6 | 3.7 | 3.3 | 57 | 270 | Yes | 512 GB | Liquid Cooled, Supporting Maximum Intel SGX Enclave Capacity |
| 8368 | 38 | 76 | 2.4 | 3.4 | 3.2 | 57 | 270 | Yes | 512 GB | Optimised for highest-per-core scalable performance and supports maximum Intel SGX Enclave Capacity |
| 8362 | 32 | 64 | 2.8 | 3.6 | 3.5 | 48 | 265 | Yes | 64GB | Optimised for highest-per-core scalable performance |
| 8360Y | 36 | 72 | 2.4 | 3.5 | 3.1 | 54 | 250 | Yes | 64GB | Optimised for highest-per-core scalable performance |
| 8360HL | 24 | 48 | 3 | 4.2 | 3.8 | 33 | 225 | Yes | | 4 and 8 Socket Scalable Performance |
| 8360H | 24 | 48 | 3 | 4.2 | 3.8 | 33 | 225 | Yes | | 4 and 8 Socket Scalable Performance |
| 8358P | 38 | 76 | 2.6 | 3.7 | 3.3 | 57 | 270 | Yes | 512 GB | Cloud Optimized for VM Utilisation |
| 8358 | 32 | 64 | 2.6 | 3.4 | 3.3 | 48 | 250 | Yes | 64GB | Optimised for highest-per-core scalable performance |
| 8356H | 8 | 16 | 3.9 | 4.4 | 4.3 | 35.75 | 190 | Yes | | 4 and 8 Socket Scalable Performance |
| 8354H | 18 | 36 | 3.1 | 4.3 | 4 | 24.75 | 205 | Yes | | 4 and 8 Socket Scalable Performance |
| 8353H | 18 | 36 | 2.5 | 3.8 | 3.3 | 24.75 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 8352M | 32 | 64 | 2.3 | 3.5 | 3.1 | 54 | 225 | Yes | 64GB | Media Processing Optimized |
| 8352Y | 32 | 64 | 2.2 | 3.4 | 2.8 | 48 | 205 | Yes | 64GB | Scalable Performance |
| 8352V | 36 | 72 | 2.1 | 3.5 | 2.5 | 54 | 1995 | Yes | 8 GB | Cloud Optimized for VM Utilisation |
| 8352S | 32 | 64 | 2.2 | 3.4 | 2.8 | 48 | 205 | Yes | 512 GB | Supporting Maximum Intel SGX Enclave Capacity |
| 8351N | 36 | 72 | 2.4 | 3.5 | 3.1 | 54 | 225 | Yes | 64GB | Single Socket Optimized, Networking/NFV Optimized |

| Model | Cores | Threads | Base (GHz) | Single Core Turbo (GHz) | All Core Turbo (GHz) | Cache (MB) | TDP (W) | Support for Intel Optane Persistent Memory 200 Series | Intel SGX Enclave capacity per processor | Features |
|---------------|-------|---------|------------|-------------------------|----------------------|------------|---------|---|--|---|
| 6348H | 24 | 48 | 2.3 | 4.2 | 3.1 | 33 | 165 | Yes | | 4 and 8 Socket Scalable Performance |
| 6348 | 28 | 56 | 2.6 | 3.5 | 3.4 | 42 | 235 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6354 | 18 | 36 | 3 | 3.6 | 3.6 | 39 | 205 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6346 | 16 | 32 | 3.1 | 3.6 | 3.6 | 36 | 205 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6342 | 24 | 48 | 2.8 | 3.5 | 3.3 | 36 | 230 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6338 | 32 | 64 | 2 | 3.2 | 2.6 | 48 | 205 | Yes | 64 GB | Scalable Performance |
| 6338T | 24 | 48 | 2.1 | 3.4 | 2.7 | 36 | 165 | Yes | 64 GB | Long-life use and NEBS-Thermal Friendly |
| 6338N | 32 | 64 | 2.2 | 3.5 | 2.7 | 48 | 185 | Yes | 64 GB | Networking/NFV Optimized |
| 6336Y | 24 | 48 | 2.4 | 3.6 | 3 | 36 | 185 | Yes | 64 GB | Scalable Performance |
| 6334 | 18 | 36 | 3.6 | 3.7 | 3.6 | 18 | 165 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6330 | 28 | 56 | 2 | 3.1 | 2.6 | 42 | 205 | Yes | 64 GB | Scalable Performance |
| 6330N | 28 | 56 | 2.2 | 3.4 | 2.6 | 42 | 165 | Yes | 64 GB | Networking/NFV Optimized |
| 6330H | 24 | 48 | 2 | 3.7 | 2.8 | 33 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 6328HL | 16 | 32 | 2.8 | 4.3 | 3.7 | 22 | 165 | Yes | | 4 and 8 Socket Scalable Performance |
| 6328HL | 16 | 32 | 2.8 | 4.3 | 3.7 | 22 | 165 | Yes | | 4 and 8 Socket Scalable Performance |
| 6326 | 16 | 32 | 2.9 | 3.5 | 3.3 | 24 | 185 | Yes | 64 GB | Optimised for highest-per-core scalable performance |
| 6314U | 32 | 64 | 2.3 | 3.4 | 2.9 | 48 | 205 | Yes | 64 GB | Single Socket Optimized |
| 6312U | 24 | 48 | 2.4 | 3.6 | 3.1 | 36 | 185 | Yes | 64 GB | Single Socket Optimized |
| 5320 | 26 | 52 | 2.2 | 3.4 | 2.8 | 39 | 185 | Yes | 64 GB | Scalable Performance |
| 5320H | 20 | 40 | 2.4 | 4.2 | 3.3 | 27.5 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 5320T | 20 | 40 | 2.3 | 3.5 | 2.9 | 30 | 150 | Yes | 64 GB | Long-life use and NEBS-Thermal Friendly |
| 5318Y | 24 | 48 | 2.1 | 3.4 | 2.6 | 36 | 165 | Yes | 64 GB | Scalable Performance |
| 5318H | 18 | 36 | 2.5 | 3.8 | 3.3 | 24.75 | 150 | Yes | | 4 and 8 Socket Scalable Performance |
| 5318N | 24 | 48 | 2.1 | 3.4 | 2.7 | 36 | 150 | Yes | 64 GB | Networking/NFV Optimized |

| Model | Cores | Threads | Base (GHz) | Single Core Turbo (GHz) | All Core Turbo (GHz) | Cache (MB) | TDP (W) | Support for Intel Optane Persistent Memory 200 Series | Intel SGX Enclave capacity per processor | Features |
|--------------|-------|---------|------------|-------------------------|----------------------|------------|---------|---|--|---|
| 5318S | 24 | 48 | 2.1 | 3.4 | 2.6 | 36 | 165 | Yes | 512 GB | Supporting Maximum Intel SGX Enclave Capacity |
| 4316 | 20 | 40 | 2.3 | 3.4 | 2.8 | 30 | 150 | | 8 GB | Scalable Performance |
| 4314 | 16 | 32 | 2.4 | 3.4 | 2.9 | 24 | 135 | Yes | 8 GB | Scalable Performance |
| 4310 | 12 | 24 | 2.1 | 3.3 | 2.7 | 18 | 120 | | 8 GB | Scalable Performance |
| 4310T | 10 | 20 | 2.3 | 3.4 | 2.9 | 15 | 105 | | 8 GB | Long-life use and NEBS-Thermal Friendly |
| 4309Y | 8 | 16 | 2.8 | 3.6 | 3.4 | 12 | 105 | | 8 GB | Scalable Performance |